

Process parameters

Process Parameters	2 μ m (5 volts & 3volts)	Units
Metal I pitch (width / space)	2 / 2	μ m
Metal II pitch (width / space)	2.6 / 2.4	μ m
Poly pitch (width / space)	2 / 2	μ m
Contact	2 x 2	μ m
Via	2.4 x 2.4	μ m
Gate geometry	2	μ m
P-well junction depth	4	μ m
N+ junction depth	0.20	μ m
P+ junction depth	0.28	μ m
Gate oxide thickness	325	Å
Inter poly oxide thick.	500	Å

Features

- Double Poly / Double Metal
- 4 μ m Poly and Metal 1 Pitch
- 320 ps Delay per stage (Ring Osc.)
- 5.5 Volts Maximum Operating Voltage
- 2.7~3.6 Volts Low Voltage Option
- Shrinkable to Mitel 1.5 μ m Process
- ProToDuction™ Option for low cost prototypes
- 150mm Wafers

Description

The 2 μ m P-Well process provides flexibility, speed and packing density needed in mixed signal designs. The aggressive design rules make it comparable to most 1.5 μ m processes. Also, the MOSFET transistors are designed with very shallow source-drain junctions and a thin gate oxide to improve speed. A low voltage option is available for 3 volts applications. It offers low and matched threshold voltages for improved dynamic range needed in mixed analog/digital applications.

MOSFET Electrical parameters

Electrical Parameters	2 MICRON - 5 volts						2 MICRON - 3 volts						Units	Conditions
	N Channel min. typ. max.			P Channel min. typ. max.			N Channel min. typ. max.			P Channel min. typ. max.				
Vt (10x2μm)	0.55	0.70	0.85	0.55	0.70	0.85	0.35	0.50	0.65	0.35	0.50	0.65	V	saturation
Ids (10x2μm)	160			70			175			80			μA/μm	Vds=Vgs=5volts
Gain β (10x2μm)	325			120			325			120			μA/V²	
Body Factor (50x50μm)	0.40			0.40			0.35			0.35			∂V̄	
Bvdss	10	12		10	13		10	12		10	13		V	Ids=100nA
Subthreshold Slope	100			100									mV/dec.	Vds=0.1v
Substrate Current	0.25 0.34						0.25 0.34						μA/μm	Vds=5.5v; Vgs=2.7v
Field Threshold	10	18		10	17		10	18		10	17		V	Ids = 14μA
L Effective	1.8			1.7			1.8			1.7			μm	L drawn = 2μm

2 Micron CMOS Process Family (cont'd)

Capacitances (fF/μm²)

	2 μm 5 volts & 3 volts		
	min.	typ.	max.
Inter-poly	.62	.73	.84
Gate oxide	0.99	1.06	1.15
N+ Junction		.195	
P+ Junction		.138	

Bipolar gain¹

	2 μm 5 volts		
	min.	typ.	max.
NPN vertical		300	

¹Test condition : Vce = 5 volts

FIG 1: I-V Characteristics for a 50x2μm N-MOSFET (2μm 5 volts process)

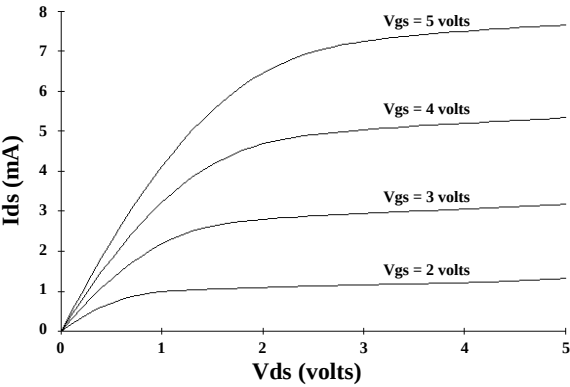


FIG 2: I-V Characteristics for a 50x2μm P-MOSFET (2μm 5 volts process)

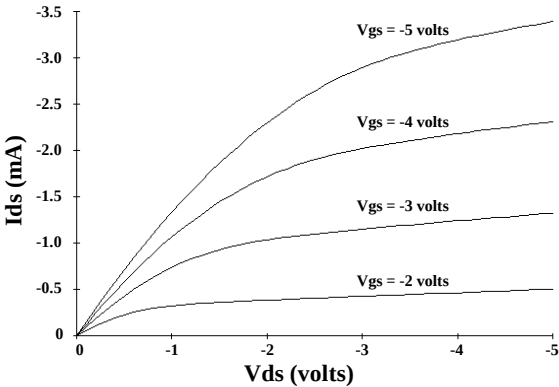


FIG 3: Subthreshold Characteristics at Vds=0.1 volts for a 50x2μm N-MOSFET (2μm 5 volts Process)

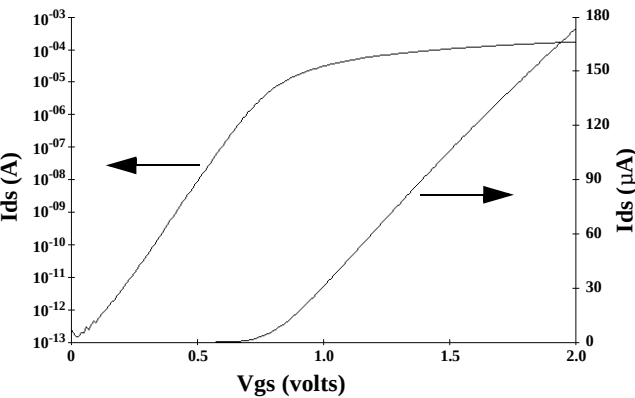
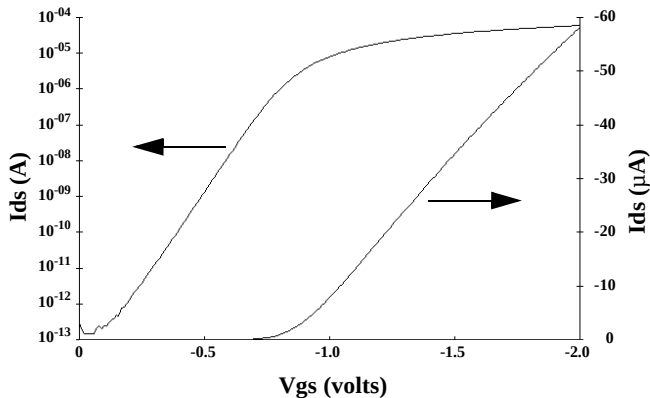


FIG 4: Subthreshold Characteristics at Vds=-0.1 volts for a 50x2μm P-MOSFET (2μm 5 volts Process)



Note: These values are for guidance only. Many of them can be adjusted to suit customer requirements. For full process specifications contact a Dalsa Semiconductor sales office or representative.